

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (original) An electronic device comprising:

a plurality of external terminals each having a base member and a metal thin film formed in direct contact with a surface of the base member,

the metal thin film being made of an alloy of tin and bismuth and the bismuth being contained in the alloy so as to satisfy any one of the following conditional expressions;

(a) $20 \leq X_m \leq 25$ and $0.5 \leq C_{am} \leq 4.5$,

(b) $15 \leq X_m \leq 20$ and $0.7 \leq C_{am} \leq 4.5$,

(c) $10 < X_m \leq 15$ and $4.5 \leq C_{am} \leq 6.0$,

wherein X_m indicating the thickness (MIC) of the metal thin film and C_{am} indicating wt % of the bismuth in the metal thin film.

2. (original) An electronic device comprising:

a plurality of external terminals each having a base member and a metal thin film formed in direct contact with a surface of the base member,

the metal thin film being made of an alloy of tin and bismuth and the bismuth being contained in the alloy so as to satisfy any one of the following conditional expressions;

(a) $10 < X_m \leq 25$, $0.5 \leq C_{am} \leq 6.0$ and $-8C_{am} + 46 < X_m \leq -8C_{am} + 54$,

(b) $10 < X_m \leq 25$, $0.5 \leq C_{am} \leq 6.0$ and $-5C_{am} + 25 \leq X_m \leq -8C_{am} + 46$,

(c) $10 < X_m \leq 25$, $0.5 \leq C_{am} \leq 6.0$ and $-5C_{am} + 15 \leq X_m < -5C_{am} + 25$,

wherein X_m indicating the thickness (MIC) of the metal thin film and C_{am} indicating wt % of the bismuth in the metal thin film.

3-4. (cancelled)

5. (original) The electronic device as claimed in claim 1, wherein the metal thin film is formed by plating.

6. (original) The electronic device as claimed in claim 1, wherein the base member is composed of a conductive material.

7. (original) The electronic device as claimed in claim 6, wherein the conductive material comprises a metal selected among the group including an iron-nickel alloy, an iron-nickel-based alloy, copper, a copper-based alloy and iron.

8. (original) The electronic device as claimed in claim 2, wherein the metal thin film is formed by plating.

9. (original) The electronic device as claimed in claim 2, wherein the base member is composed of a conductive material.

10. (original) The electronic device as claimed in claim 9, wherein the conductive material comprises a metal

selected among the group including an iron-nickel alloy, an iron-nickel-based alloy, copper, a copper-based alloy and iron.